Chip Errata for the i.MX RT1015

This document details the silicon errata known at the time of publication for the i.MX RT1015 multimedia crossover processors.

Table 1 provides a revision history for this document.

<table>
<thead>
<tr>
<th>Rev. Number</th>
<th>Date</th>
<th>Substantive Changes</th>
</tr>
</thead>
<tbody>
<tr>
<td>Rev. 3</td>
<td>08/2021</td>
<td>• Added the following errata:</td>
</tr>
<tr>
<td></td>
<td></td>
<td>- ERR050606</td>
</tr>
<tr>
<td></td>
<td></td>
<td>- ERR050607</td>
</tr>
<tr>
<td></td>
<td></td>
<td>- ERR050538</td>
</tr>
<tr>
<td></td>
<td></td>
<td>• Updated the following errata:</td>
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<td></td>
<td></td>
<td>- ERR050101</td>
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<tr>
<td>Rev. 2</td>
<td>01/2021</td>
<td>• Added the following errata:</td>
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<tr>
<td></td>
<td></td>
<td>- ERR050143</td>
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<tr>
<td></td>
<td></td>
<td>• Removed the following errata:</td>
</tr>
<tr>
<td></td>
<td></td>
<td>- ERR007265 (replace ERR007265 with ERR050143)</td>
</tr>
<tr>
<td></td>
<td></td>
<td>• Updated the Figure 1, &quot;Revision Level to Part Marking Cross-Reference,&quot;</td>
</tr>
<tr>
<td>Rev. 1</td>
<td>06/2019</td>
<td>• Added the following errata:</td>
</tr>
<tr>
<td></td>
<td></td>
<td>- ERR011572</td>
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<tr>
<td></td>
<td></td>
<td>- ERR050101</td>
</tr>
<tr>
<td></td>
<td></td>
<td>- ERR050130</td>
</tr>
<tr>
<td></td>
<td></td>
<td>- ERR050144</td>
</tr>
<tr>
<td></td>
<td></td>
<td>- ERR050194</td>
</tr>
<tr>
<td>Rev. 0</td>
<td>01/2019</td>
<td>• Initial version</td>
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**Figure 1** provides a cross-reference to match the revision code to the revision level marked on the device.

<table>
<thead>
<tr>
<th>Qualification Level</th>
<th>M</th>
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<tbody>
<tr>
<td>Prototype Samples</td>
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<tr>
<td>Mass Production</td>
<td>M</td>
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<tr>
<td>Special</td>
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<table>
<thead>
<tr>
<th>Part # series</th>
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<tr>
<td>IMX RT</td>
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<table>
<thead>
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<td>Reserved</td>
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<table>
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<td>RT105x</td>
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<td>RT106x</td>
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<th>Silicon Rev</th>
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<tr>
<td>A0</td>
<td>A</td>
</tr>
<tr>
<td>A1</td>
<td>B</td>
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<table>
<thead>
<tr>
<th>Core Frequency</th>
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<tr>
<td>400 MHz</td>
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<tr>
<td>500 MHz</td>
<td>5</td>
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<tr>
<td>600 MHz</td>
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<table>
<thead>
<tr>
<th>Package Type</th>
<th>VV</th>
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<tbody>
<tr>
<td>196MAPBGA, 12 x 12 mm, 0.8 mm pitch</td>
<td>VJ</td>
</tr>
<tr>
<td>196MAPBGA, 10 x 10 mm, 0.65 mm pitch</td>
<td>VL</td>
</tr>
<tr>
<td>144LQFP, 20 x 20 mm, 0.5 mm pitch</td>
<td>AG</td>
</tr>
<tr>
<td>100LQFP, 14 x 14 mm, 0.5 mm pitch</td>
<td>AF</td>
</tr>
<tr>
<td>80LQFP, 12 x 12 mm, 0.5 mm pitch</td>
<td>AE</td>
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<table>
<thead>
<tr>
<th>Temperature (Tj)</th>
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<tbody>
<tr>
<td>Consumer: 0 to + 95 °C</td>
<td>D</td>
</tr>
<tr>
<td>Industrial: -40 to +105 °C</td>
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</table>

**Figure 1. Revision Level to Part Marking Cross-Reference**

For details on the Arm® configuration used on this chip (including Arm module revisions), please see the “Platform configuration” section of the “Arm Cortex®-M7 Platform” chapter of the *i.MX RT1015 Crossover Processor Reference Manual (IMXRT1015RM)*.
Table 2 summarizes errata on the i.MX RT1015.

### Table 2. Summary of Silicon Errata

<table>
<thead>
<tr>
<th>Errata</th>
<th>Name</th>
<th>Solution</th>
<th>Page</th>
</tr>
</thead>
<tbody>
<tr>
<td>ADC</td>
<td>ERR011164 ADC: ADC_ETC fails to clear the ADC_ETC request signals automatically after receiving DMA ack</td>
<td>No fix scheduled</td>
<td>5</td>
</tr>
<tr>
<td>CCM</td>
<td>ERR006223 CCM: Failure to resume from Wait/Stop mode with power gating</td>
<td>No fix scheduled</td>
<td>6</td>
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<tr>
<td></td>
<td>ERR050143 CCM: SoC will enter low power mode before the Arm CPU executes WFI when improper low power sequence is used</td>
<td>No fix scheduled</td>
<td>7</td>
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<tr>
<td>Cortex-M7</td>
<td>ERR011572 Cortex-M7: Write-Trough stores and loads may return incorrect data</td>
<td>No fix scheduled</td>
<td>8</td>
</tr>
<tr>
<td>FlexSPI</td>
<td>ERR011207 FlexSPI: When FLEXSPI_AHBCR[PREFETCHEN] is set, incorrect data can be returned in rare conditions</td>
<td>No fix scheduled</td>
<td>9</td>
</tr>
<tr>
<td></td>
<td>ERR011377 FlexSPI: FlexSPI DLL lock status bit not accurate due to timing issue</td>
<td>No fix scheduled</td>
<td>10</td>
</tr>
<tr>
<td>LPSPI</td>
<td>ERR050606 LPSPI: TCR value does not get resampled when polling the register</td>
<td>No fix scheduled</td>
<td>11</td>
</tr>
<tr>
<td></td>
<td>ERR050607 LPSPI: TCR[Framesz] can be ignored when TCR[TXMSK] = 1b1</td>
<td>No fix scheduled</td>
<td>12</td>
</tr>
<tr>
<td>PIT</td>
<td>ERR050130 PIT: Temporary incorrect value reported in LMTR64H register in lifetimer mode</td>
<td>No fix scheduled</td>
<td>13</td>
</tr>
<tr>
<td>QTMR</td>
<td>ERR050194 QTMR: Overflow flag and related interrupt cannot be generated when the timer is configured as upward count mode</td>
<td>No fix scheduled</td>
<td>14</td>
</tr>
<tr>
<td>SAI</td>
<td>ERR011096 SAI: The internal bit clock cannot be generated when BCI = 1</td>
<td>No fix scheduled</td>
<td>15</td>
</tr>
<tr>
<td></td>
<td>ERR011150 SAI: Internally generated receive or transmit BCLK cannot be re-enabled if it is first disabled when RCR2[DIV] or TCR2[DIV] &gt; 0</td>
<td>No fix scheduled</td>
<td>16</td>
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<tr>
<td></td>
<td>ERR050144 SAI: Setting FCONT = 1 when TMR &gt; 0 may not function correctly</td>
<td>No fix scheduled</td>
<td>17</td>
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<tr>
<td>SOC</td>
<td>ERR050538 SOC: Potential boot failure on system reset if SJC_DISABLE fuse is blown</td>
<td>No fix scheduled</td>
<td>18</td>
</tr>
<tr>
<td>SNVS</td>
<td>ERR011165 SNVS: Invalid ECC check failure</td>
<td>No fix scheduled</td>
<td>19</td>
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</table>
Table 2. Summary of Silicon Errata (continued)

<table>
<thead>
<tr>
<th>Errata</th>
<th>Name</th>
<th>Solution</th>
<th>Page</th>
</tr>
</thead>
<tbody>
<tr>
<td>ERR006281</td>
<td>USB: Incorrect DP/DN state when only VBUS is applied</td>
<td>No fix scheduled</td>
<td>20</td>
</tr>
<tr>
<td>ERR050101</td>
<td>USB: Endpoint conflict issue in device mode</td>
<td>Fix in A1 revision</td>
<td>21</td>
</tr>
</tbody>
</table>
ERR011164  ADC: ADC_ETC fails to clear the ADC_ETC request signals automatically after receiving DMA ack

Description:
If enable ADC_ETC to trigger DMA transfer, the DMA transfer data send ack out. It does not clear the request signals automatically and continue to trigger DMA.

Projected Impact:
This issue can lead to DMA failure when working with ADC_ETC.

Workarounds:
Configuring two DMA channels for ADC_ETC data transfer. The first DMA channel with low priority triggered by ADC_ETC request is to transfer ADC_ETC data. The second DMA channel with high priority links to the first channel is to clear request of ADC_ETC by writing DMA_CTRL register. Both channel’s priority need to be higher than any channel used by other peripherals. This solution is result in DMA to transfer ADC_ETC data twice for one request signal and application need handle the redundant data properly.

Proposed Solution:
No fix scheduled

Software Status:
Software workaround is not in SDK.
ERR006223

CCM: Failure to resume from Wait/Stop mode with power gating

Description:
When entering Wait/Stop mode with power gating of the Arm core(s), if an interrupt arrives during the power-down sequence, the system could enter an unexpected state and fail to resume.

Projected Impact:
Device might fail to resume from low-power state.

Workarounds:
Use REG_BYPASS_COUNTER (RBC) to hold off interrupts when the PGC unit is in the middle of the power-down sequence. The counter needs to be set/cleared only when there are no interrupts pending. The counter needs to be enabled as close to the WFI (Wait For Interrupt) state as possible. The following equation can be used to aid determination of the RBC counter value:
The PREG_BYPASS_COUNT value is equal or greater than 2.

Proposed Solution:
No fix scheduled

Software Status:
Software workaround is in SDK.
ERR050143  CCM: SoC will enter low power mode before the Arm CPU executes WFI when improper low power sequence is used

Description:
When software tries to enter the low power mode with the following sequence, SoC enters the low power mode before the Arm CPU executes the WFI instructions.
• Set CCM_CLPCR[1:0] to 2'b00
• Arm CPU enters WFI
• Arm CPU wakes up from an interrupt event, which is masked by GPC or not visible to GPC, such as an interrupt from local timer.
• Set CCM_CLPCR[1:0] to 2'b01 or 2'b10
• Arm CPU executes WFI
Before the last step, SoC enters the WAIT mode if CCM_CLPCR[1:0] is set to 2'b01, or enters the STOP mode if CCM_CLPCR[1:0] is set to 2'b10.

Workarounds:
Software workaround:
1. Trigger IRQ #41 (IOMUX), which is always pending by setting IOMUXC_GPR_GPR1[12] bit
2. Unmask IRQ #41 in GPC before setting the CCM low power mode
3. Mask IRQ #41 right after the CCM low power mode is set (set CCM_CLPCR[1:0])

Proposed Solution:
No fix scheduled

Software Status:
Software workaround is in SDK
ERR011572  Cortex-M7: Write-Trough stores and loads may return incorrect data

Description:

Arm errata 1259864

If a particular sequence of stores and loads is performed on the Cortex-M7 core to Write-Through memory, and some timing-based internal conditions are met, then a load may not have the last data stored to that address.

This erratum can only occur if the loads and stores are to Write-Through memory. The following methods enable write-through mode of the cache:

1. The Memory Protection Unit (MPU) has been programmed to set this address as Write-Through.
2. The default memory map is being used, and this address is Write-Through in the default memory map.
3. The memory is cacheable, and the CM7_CACR.FORCEWT bit is set.
4. The memory is cacheable, shared, and the CM7_CACR.SIWT bit is set.

Following sequence is required for this erratum to occur:

1. The address of interest must be in the data cache.
2. A Write-Through store is performed to the same double-word as the address of interest.
3. One of the following:
   - A linefill is started (to a different cacheline to the address of interest) that allocates to the same set and way as the address of interest.
   - An Error Correcting Code (ECC) error is observed anywhere in the data cache.
   - A data cache maintenance operation without a following Data Synchronization Barrier (DSB).
4. A store to the address of interest.
5. A load to the address of interest.

If certain specific timing conditions are met, the load get the data from the first store, or from what was in the cache at the start of the sequence instead of the data from the second store.

Under these conditions, a load can return incorrect data.

Workarounds:

There is no direct workaround for this erratum.

Where possible, Arm is recommended that using the MPU to change the attributes on any Write-Through memory to Write-Back memory. If this is not possible, it might be necessary to disable the cache for sections of code that access Write-Through memory.

Proposed Solution:

No fix scheduled
ERR011207   FlexSPI: When FLEXSPI_AHBCR[PREFETCHEN] is set, incorrect data can be returned in rare conditions

Description:

When prefetching is enabled (FLEXSPI_AHBCR[PREFETCHEN]) for non-cacheable space, there are conditions where write-read order might not be guaranteed. The problem can occur if data is written and then read back using AHB interface, while a region containing the data location is in the process of being loaded into the FlexSPI’s AHB Rx buffer.

Workarounds:

There are two workarounds:

• If FlexSPI space is not cached (configured as device or strongly-ordered type in the MPU), then FLEXSPI_AHB_RXBUFnCR0[PREFETCHEN] can be cleared.

• If the write is critical and the following read is to the same address, FlexSPI_STS0[SEQIDLE] bit can be checked to make sure the write has completed (SEQIDLE is 1) before issuing the subsequent read.

Proposed Solution:

No fix scheduled

Software Status:

Software workaround is not in SDK.
ERR011377 FlexSPI: FlexSPI DLL lock status bit not accurate due to timing issue

Description:

After configuring DLL and the lock status bit is set, the data may be wrong if read/write immediately from FLEXSPI based external flash due to timing issue.

Workarounds:

Add delay time (100 NOP) again after the DLL lock status is set.

Proposed Solution:

No fix scheduled

Software Status:

No software workaround available
ERR050606  LPSPI: TCR value does not get resampled when polling the register

Description:

Reading the Transmit Command Register (TCR) will return the current state to the command register.

Following a write to the TCR if user continuously reads the TCR (polls the register), then the read content no longer represents the content of the TCR if it updates due to internal logic follow the first read. The same value shall continue to be read.

Workarounds:

After reading the TCR must always access a different register in between subsequent reads from TCR.
ERR050607  

**LPSPI: TCR[FRAMESZ] can be ignored when TCR[TXMSK] = 1b1**

**Description:**

TCR is used to write new command word to the LPSPI transmit FIFO. TCR[FRAMESZ] configure the frame size of the data to be transmitted in number of bits equal to (FRAMESZ + 1). When TCR[TXMSK] is set, transmit data are marked (no data is loaded from transmit FIFO and output pin is tristated). In Master mode, the Transmit Data Mask bit will initiate a new transfer which cannot be aborted by another command word; the Transmit Data Mast bit will be cleared by hardware at the end of the transfer. TCR[CONTC] controls the continuous transfer will keep the PCS asserted at the end of the frame size until a command word is received that starts a new frame.

If command word is written with TCR[TXMSK] = 1, TCR[FRAMESZ] > 32, and next command word with TCR[CONTC] = 0 in the FIFO, then at the end of any 32-bit word of the first command, the frame will terminate early and negate PCS.

**Workarounds:**

There are two workarounds:

- Do not write a second command word after writing command word with TXMSK = 1 and FRAMESZ > 32 until the first one has completed.
- Divide the command word into multiple command words with TXMSK = 1 and FRAMESZ = 32 (or remainder) using a continuous transfer.
Description:

When the Programmable interrupt timer (PIT) module is used in lifetimer mode, timer 0 and timer 1 are chained and the timer load start value (LDVAL0[TSV] and LDVAL1[TSV]) are set according to the application need for both timers. When timer 0 current time value (CVAL0[TVL]) reaches 0x0 and subsequently reloads to LDVAL0[TSV], then timer 1 CVAL1[TVL] should decrement by 0x1.

However this decrement does not occur until one cycle later, therefore a read of the PIT upper lifetime timer register (LTMR64H) is followed by a read of the PIT lower lifetime timer register (LTMR64L) at the instant when timer 0 has reloaded to LDVAL0[TSV] and timer 1 is yet to be decremented in next cycle then an incorrect timer value in LTMR64H[LTH] is expected.

Workarounds:

In lifetimer mode, if the read value of LTMR64L[LTL] is equal to LDVAL0[TSV], then read both LTMR64H and LTMR64L registers for one additional time to obtain the correct lifetime value.

Proposed Solution:

No fix scheduled

Software Status:

Software workaround is not in SDK.
ERR050194  QTMR: Overflow flag and related interrupt cannot be generated when the timer is configured as upward count mode

Description:

1. Overflow flag and related interrupt cannot be generated successfully in upward count mode.
2. When TMR_CTRL[OUTMODE] is set to 110b, OFLAG output is not cleared on counter rollover when the timer counts upward.

Workarounds:

For item 1, using compare interrupt instead of overflow interrupt by setting compare value to 0xFFFF. The compare interrupt has the same timing effect as overflow interrupt in this way.
For item 2, there is no workaround.

Proposed Solution:

No fix scheduled

Software Status:

Software workaround is not in SDK.
ERR011096  SAI: The internal bit clock cannot be generated when BCI = 1

Description:
When SAI transmitter or receiver is configured for the internal bit clock with BCI = 1, the bit clock cannot be generated for either of the following two configurations:
1. SYNC = 00 and BCS = 0
2. SYNC = 01 and BCS = 1

Projected Impact:
The SAI bit clock cannot be generated properly.

Workarounds:
When SAI transmitter or receiver is configured for the internal bit clock with BCI = 1, using one of the following two configurations:
1. SYNC = 01 and BCS = 0
2. SYNC = 00 and BCS = 1

Proposed Solution:
No fix scheduled

Software Status:
Software workaround is not in SDK.
ERR011150  SAI: Internally generated receive or transmit BCLK cannot be re-enabled if it is first disabled when RCR2[DIV] or TCR2[DIV] > 0

Description:
The receive or transmit bit clock (BCLK) is internally generated and enabled with DIV > 0. When it is disabled, due to software or Stop mode entry, the BCLK is enabled again. Then the clock cannot be generated.

Projected Impact:
The SAI bit clock cannot be generated.

Workarounds:
If the receive or transmit BCLK is internally generated and a DIV value is greater than 0, the SAI must be reset before the BCLK is re-enabled. This is achieved by writing the SR bit in the respective RCSR or TCSR register first to 1, and then immediately write it to 0.

Proposed Solution:
No fix scheduled

Software Status:
Software workaround is not in SDK.
ERR050144  SAI: Setting FCONT = 1 when TMR > 0 may not function correctly

Description:
When FCONT = 1 the transmitter will recover after a FIFO error when the FIFO is no longer empty and starting again from the same word in the following frame where the error occurred. Configuring TMR > 0 will configure one or more words in the frame to be masked (nothing transmitted during that slot). If anything other than the last word(s) in the frame are masked when FCONT = 1 and a FIFO Error Flag is set, then the transmitter will not recover and will set FIFO Error Flag during each frame.

Workarounds:
To avoid this issue, set FCONT in TCR4 to be 0.

Proposed Solution:
No fix scheduled

Software Status:
Software workaround is not in SDK.
ERR050538 SOC: Potential boot failure on system reset if SJC_DISABLE fuse is blown

Description:
By default, the JTAG/SWD clock is pulled high reset. When the SJC_DISABLE fuse is blown the clock is low. The fuses are reloaded during a system reset, so there is a window between the system reset assertion and fuse loading completion, during which the clock is high. When the fuses are loaded the clock will go low, causing a transition from high to low. There is another clock transition from low to high on a subsequent system reset. The clock toggles can cause the system to think JTAG/SWD is active. This causes a security violation leading to HAB boot failure.

Workarounds:
Configure the appropriate IOMUXC_SW_PAD_CTL register’s PUE and PUS fields to enable a pull resistor on one of the following signals:
• Pull JTAG_TCK/SWD_CLK low
• Pull JTAG_TRST low
• Pull JTAG_TMS/SWD_DIO high
The IOMUX registers retain state on a system reset, so this only needs to be done one time after each POR.
ERR011165  SNVS: Invalid ECC check failure

Description:
When setting LPMKCR[ZMK_ECC_EN] bit, it may generate ZMK ECC Check Failure Violation even the ZMK and its ECC values are correct.

Projected Impact:
ZMK is not usable in case the ZMK ECC check is enabled.

Workarounds:
Not enable ZMK ECC check

Proposed Solution:
No fix scheduled

Software Status:
Software workaround is not in SDK.
ERR006281  USB: Incorrect DP/DN state when only VBUS is applied

Description:
When VBUS is applied without any other supplies, incorrect communication states are possible on the data (DP/DN) signals. If VDDHIGH_IN is supplied, the problem is removed.

Projected Impact:
This issue primarily impacts applications using charger detection to signal power modes to a PMIC in an undercharged battery scenario where the standard USB current allotment is not sufficient to boot the system.

Workarounds:
Apply VDDHIGH_IN if battery charge detection is needed. Otherwise, disable charger detection by setting the EN_B bit in USB_ANALOG_USBx_CHRG_DETECTn to 1.

Proposed Solution:
No fix scheduled

Software Status:
Software workaround is not in SDK.
ERR050101  USB: Endpoint conflict issue in device mode

Description:
An endpoint conflict occurs when the USB is working in device mode during an isochronous communication. When the endpointA IN direction is an isochronous IN endpoint, and the host sends an IN token to endpointA on another device, then the OUT transaction may be missed regardless the OUT endpoint number. Generally, this occurs when the device is connected to the host through a hub and other devices are connected to the same hub. The affected OUT endpoint can be either control, bulk, isochronous, or an interrupt endpoint. After the OUT endpoint is primed, if an IN token to the same endpoint number on another device is received, then the OUT endpoint may be unprimed (cannot be detected by software), which causes this endpoint to no longer respond to the host OUT token, and thus, no corresponding interrupt occurs.

Workarounds:
Do not connect to a hub in case ISO IN endpoint(s) is used. When the hub(s) must be connected in this case, the endpoint number(s) of the ISO IN endpoint(s) should be different from the endpoint number(s) of any types of IN endpoint(s) used in any other device(s) connected to the same host.

Proposed Solution:
Fix in A1 revision
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